

WinhiSemi

VUGA044N02TA

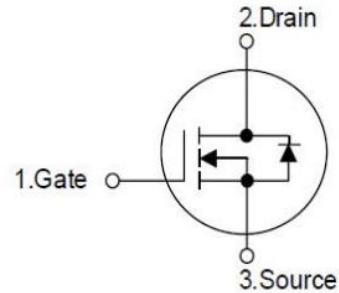
Datasheet

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General Description

VUGA044N02TA N-Channel MOSFET is based on unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics.

Symbol

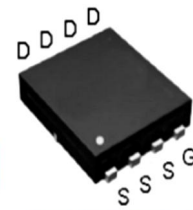


Symbol of VUGA044N02TA

Features

- Low $R_{DS(ON)}$ & FOM
- $R_{DS(ON)_{max}} = 9m\Omega @ V_{GS} = 4.5V$
- Extremely low switching loss
- Fast switching and soft recovery

Package Type



Package Type of VUGA044N02TA

Application

- Charging Circuit
- Battery Applications
- Synchronous Rectification
- High Frequency Switching

Ordering Information

Product Name	Package	Marking
VUGA044N02TA	PDFN3.3*3.3	44N02

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	±8	V
Continuous Drain Current ^{Note 1} , $T_C=25^{\circ}C$	I_D	22	A
Pulsed Drain Current ^{Note 2}	I_{DM}	66	A
Max Power Dissipation ^{Note 3} , $T_C=25^{\circ}C$	P_D	19.4	W
Avalanche Current, Single Pulse ^{Note 5}	I_{AS}	21	A
Avalanche Energy, Single Pulse ^{Note 5}	E_{AS}	66.1	mJ
Operation Junction temperature	T_J	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		6.45		°C/W
Thermal Resistance, Junction-to-Ambient ^{Note4}	$R_{\theta JA}$		62		

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_D is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^{\circ}C$.
- 5) $V_{DS}=15V, V_{GS}=4.5V, L=0.3mH, R_g=25\Omega$, starting $T_J=25^{\circ}C$.

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 8V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	0.6	0.9	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=5A$		7.2	9	$m\Omega$
		$V_{GS}=4.5V, I_D=15A$		7.2	9	$m\Omega$
Gate Resistance	R_G	$f=1MHz, \text{open drain}$		0.35		Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS}=0V$		782.8		pF
Output Capacitance	C_{oss}	$V_{DS}=10V$		565.7		pF
Reverse Transfer Capacitance	C_{rss}	$f=1MHz$		59.5		pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=15V$		7.6		ns
Rise Time	t_r	$V_{GS}=4.5V$		2.8		
Turn-off Delay Time	$t_{d(off)}$	$I_D=6A$		26.2		
Fall Time	t_f	$R_G=3\Omega$		7.4		
Switching Characteristics						
Total Gate Charge (@ $V_{GS}=8V$)	Q_g	$V_{GS}=0 \text{ to } 8V$ $V_{DS}=10V$ $I_D=15A$		18.19		nC
Total Gate Charge (@ $V_{GS}=4.5V$)	Q_g		10.24			
Gate to Source Charge	Q_{gs}		1.3			
Gate to Drain Charge	Q_{gd}		2.74			
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=12A$		0.81	1.2	V
Reverse Recovery Time	t_{rr}	$V_{DS}=10V$		27.73		ns
Reverse Recovery Charge	Q_{rr}	$I_F=12A$		14.41		nC
Peak Reverse Recovery Current	I_{rrm}	$di/dt=100A/\mu s$		0.9		A

Typical Performance Characteristics

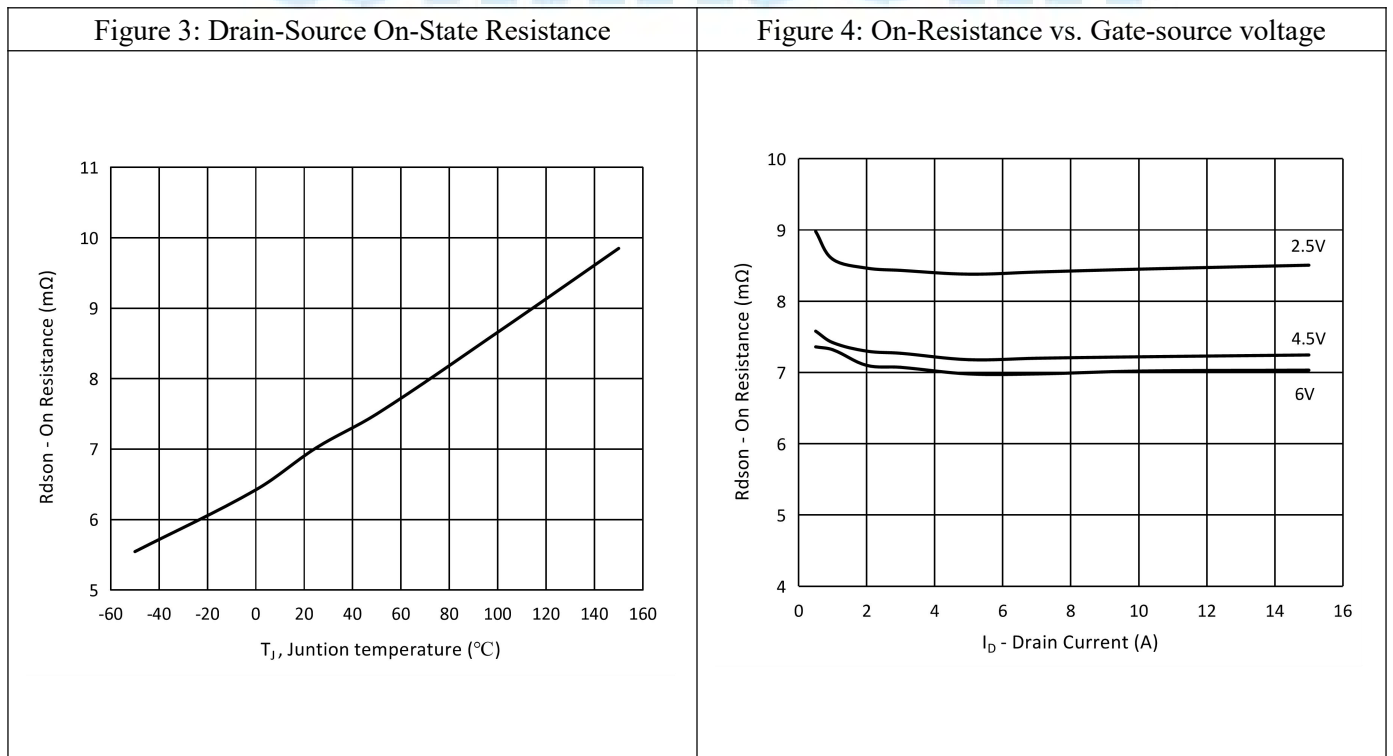
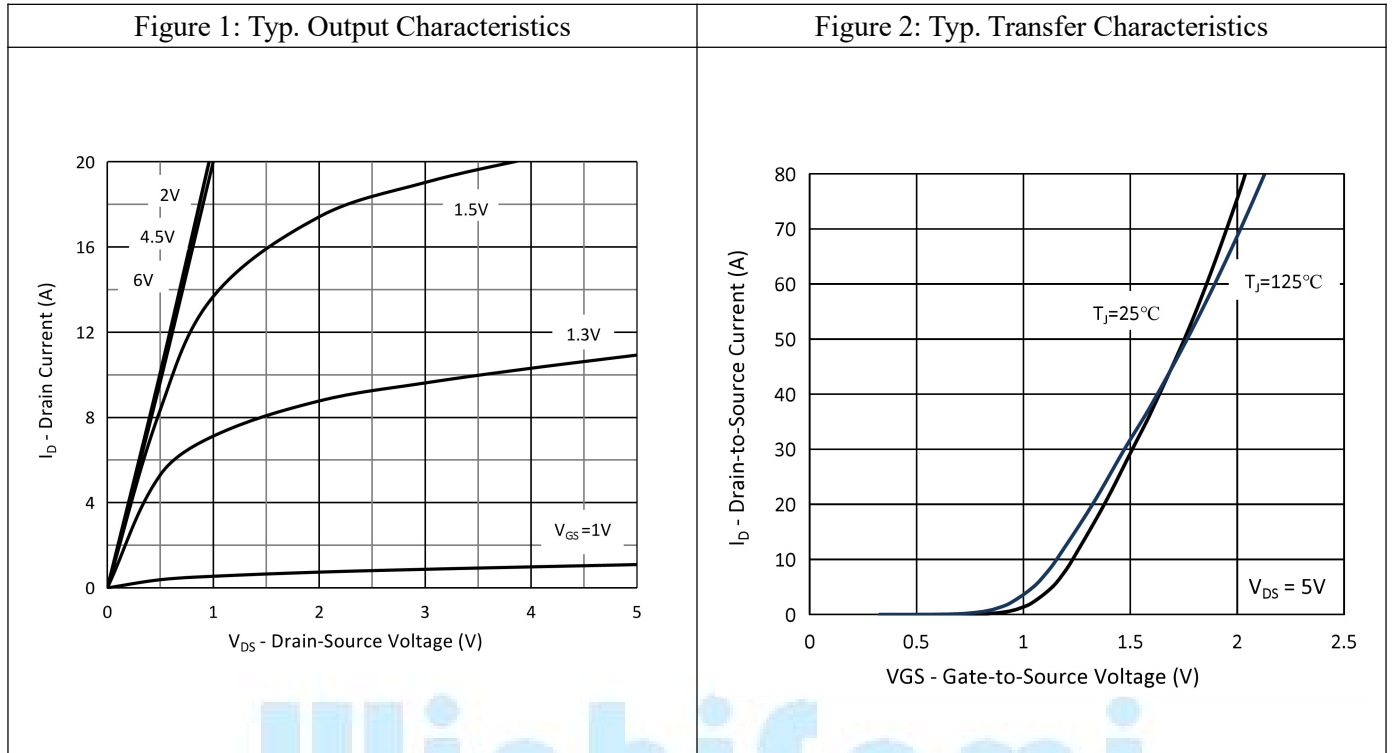


Figure 5: Typ. Capacitances

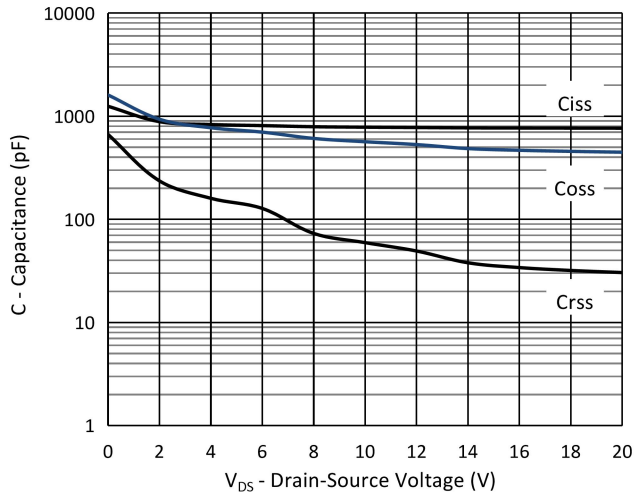


Figure 6: Gate Charge Characteristics

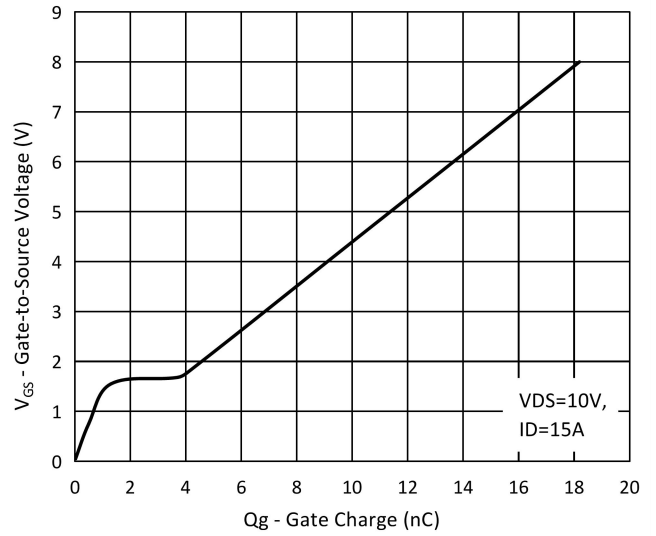


Figure 7: Forward Characteristics of Body Diode

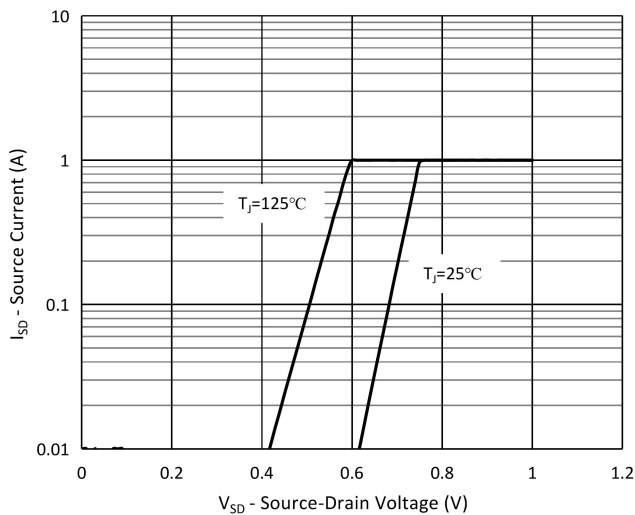


Figure 8: Safe Operating Area T_c=25°C

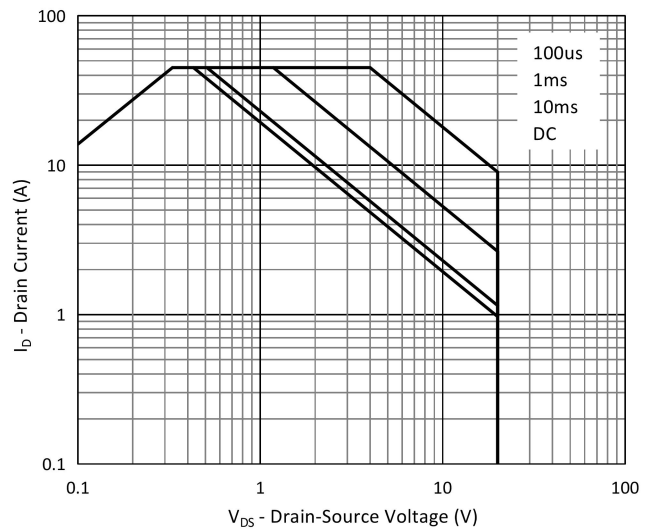


Figure 9: Power De-rating

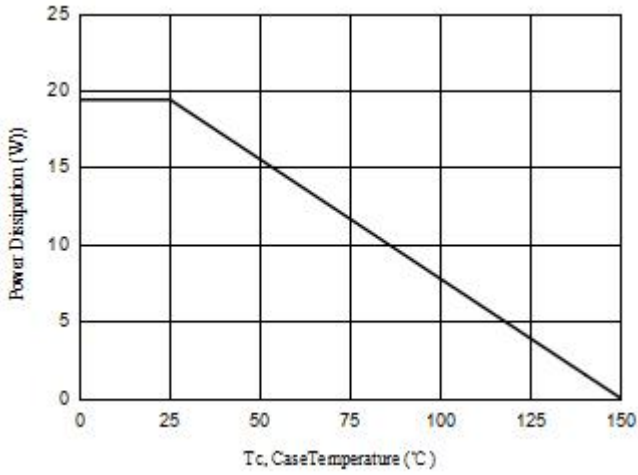


Figure 10: Current De-rating

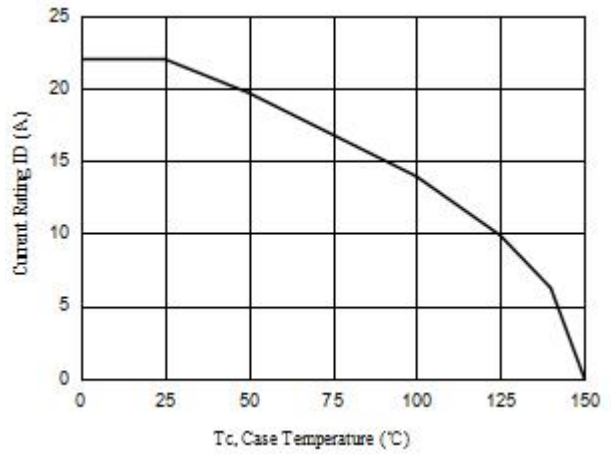


Figure 11: Single pulse power rating, Junction to case

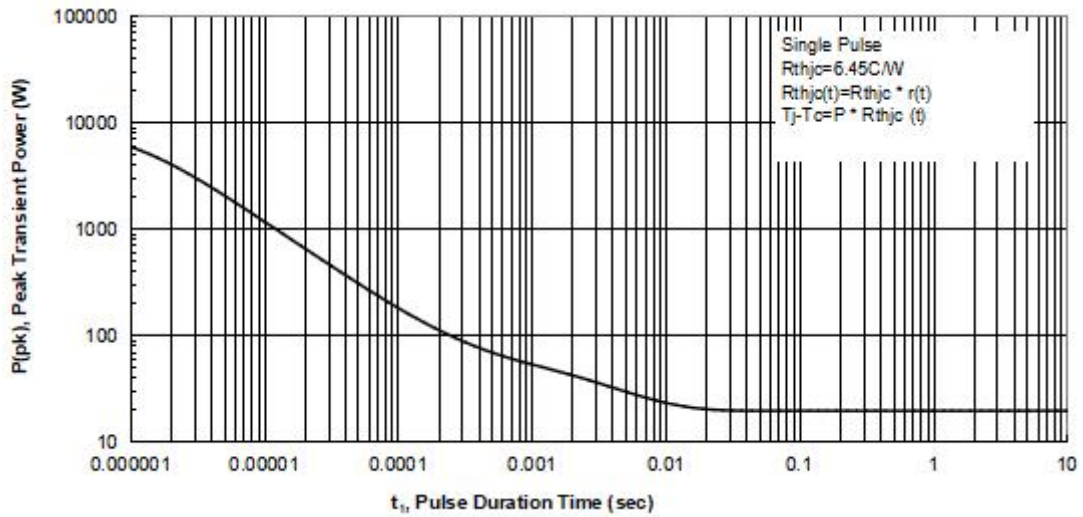
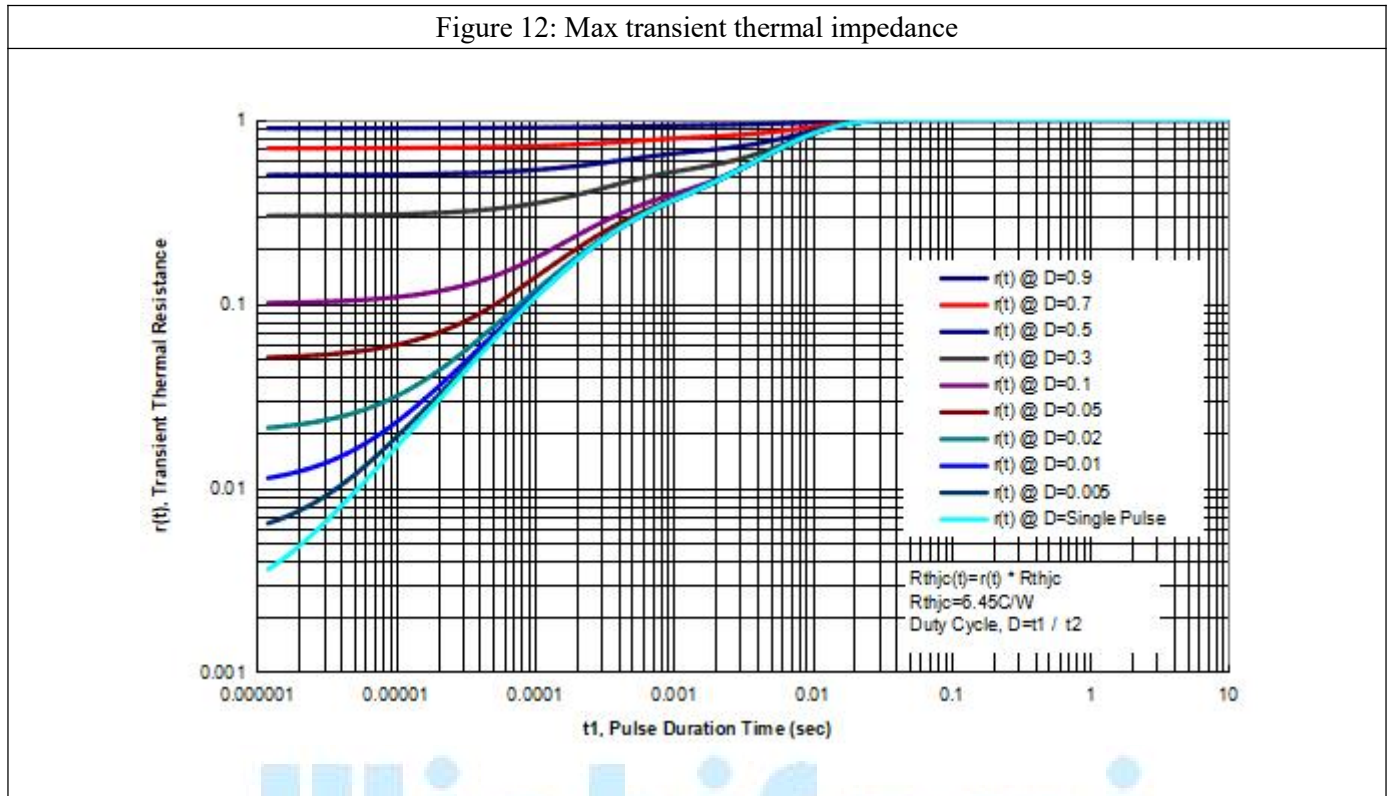
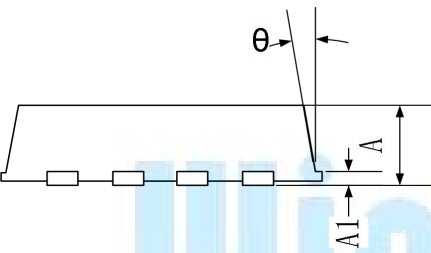
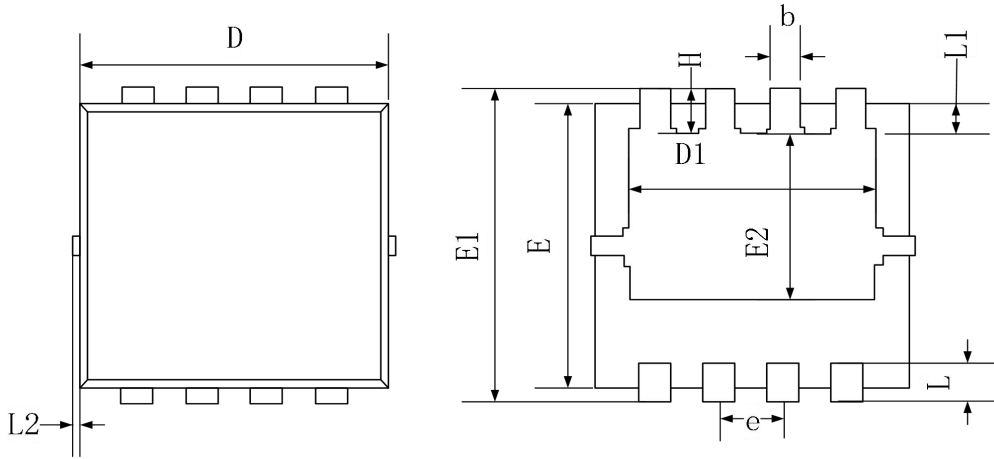


Figure 12: Max transient thermal impedance



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Mechanical Dimensions (PDFN3.3*3.3 Unit:mm)



SYMBOL	MILLIMETERS	
	MIN	MAX
A	0.70	0.90
A1	0.10	0.25
D	2.90	3.25
D1	2.25	2.69
E	2.90	3.20
E1	3.00	3.60
E2	1.35	2.20
b	0.20	0.40
e	0.65BSC	
L	0.30	0.50
L1	0.13BSC	
L2	0.00	0.20
H	0.15	0.65
θ	0°	14°

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